

Docket No.: 50432-614

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of : Customer Number: 20277

Darrell M. ERB, et al. : Confirmation Number:

Serial No.: : Group Art Unit:

Filed: March 04, 2004 : Examiner: Unknown

For: COMPOSITE TANTALUM CAPPED INLAID COPPER WITH REDUCED  
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**INFORMATION DISCLOSURE STATEMENT**

Mail Stop IDS  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

In accordance with the provisions of 37 C.F.R. 1.56, 1.97 and 1.98, the attention of the Patent and Trademark Office is hereby directed to the documents listed on the attached form PTO-1449. It is respectfully requested that the documents be expressly considered during the prosecution of this application, and that the documents be made of record therein and appear among the "References Cited" on any patent to issue therefrom.

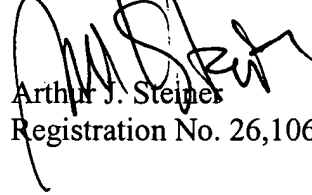
This Information Disclosure Statement is being filed within three months of the U.S. filing date OR before the mailing date of a first Office Action on the merits. No certification or fee is required.

**Serial No.:**

Please charge any shortage in fees due in connection with the filing of this paper, including extension of time fees, to Deposit Account 500417 and please credit any excess fees to such deposit account.

Respectfully submitted,

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INFORMATION DISCLOSURE CITATION IN AN APPLICATION				ATTY. DOCKET NO. 50432-614		SERIAL NO.	
(PTO-1449)				APPLICANT Darrell M. ERB, et al.			
				FILING DATE March 04, 2004		GROUP	
U.S. PATENT DOCUMENTS							
EXAMINER'S INITIALS	CITE NO.	Document Number Number-Kind Code <sub>2</sub> (if known)		Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document		Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		US	6,207,552 B1	03/27/2001	Wang et al.		
		US	6,100,184	08/08/2000	Zhao et al.		
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FOREIGN PATENT DOCUMENTS							
EXAMINER'S INITIALS	CITE NO.	Foreign Patent Document Country Codes - Number 4 - Kind Codes (if known)		Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines Where Relevant Figures Appear	Translation  Yes      No
OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)							
EXAMINER'S INITIALS	CITE NO.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.					
		E. T. OGAWA, et al., "Stress-Induced Voiding Under Vias Connected to Wide Cu Metal Leads", April 2002, p. 312-321					
		D. EDELSTEIN, et al., "A High Performance Liner for Copper Damascene Interconnects", Watson Research Center, IEEE 2001, p. 9-11					
		D. EDELSTEIN, et al., "An Optical Liner for Copper Damascene Interconnects", Conference Proceedings ULSI XVII, 2002, p. 541-547					
EXAMINER				DATE CONSIDERED			

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

1 Applicant's unique citation designation number (optional). 2 Applicant is to place a check mark here if English language Translation is attached.